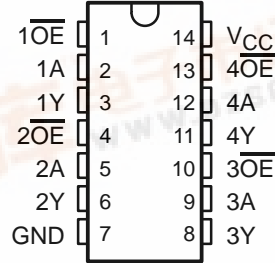


QUADRUPLE BUS BUFFER GATE WITH 3-STATE OUTPUTS

SDFS016B – JANUARY 1989 – REVISED JULY 2002

- 3-State Outputs Drive Bus Lines or Buffer Memory Address Registers

D, DB, N, OR NS PACKAGE
(TOP VIEW)



description/ordering information

The SN74F125 features independent line drivers with 3-state outputs. Each output is disabled when the associated output-enable (\overline{OE}) input is high.

ORDERING INFORMATION

TA	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP – N	Tube	SN74F125N	SN74F125N
	SOIC – D	Tube	SN74F125D	F125
		Tape and reel	SN74F125DR	
	SOP – NS	Tape and reel	SN74F125NSR	74F125
SSOP – DB	Tape and reel	SN74F125DBR	F125	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE
(each buffer)

INPUTS		OUTPUT Y
\overline{OE}	A	
L	H	H
L	L	L
H	X	Z

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



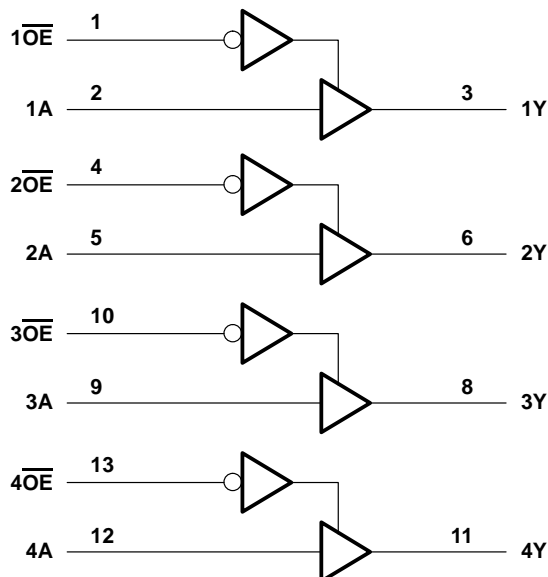
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



SN74F125 QUADRUPLE BUS BUFFER GATE WITH 3-STATE OUTPUTS

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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–1.2 V to 7 V
Input current range	–30 mA to 5 mA
Voltage range applied to any output in the disabled or power-off state	–0.5 V to 5.5 V
Voltage range applied to any output in the high state	128 mA
Current into any output in the low state	±70 mA
Package thermal impedance, θ_{JA} (see Note 2):	
D package	86°C/W
DB package	96°C/W
N package	80°C/W
NS package	76°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input voltage ratings may be exceeded provided the input current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

	MIN	NOM	MAX	UNIT
V_{CC} Supply voltage	4.5	5	5.5	V
V_{IH} High-level input voltage	2			V
V_{IL} Low-level input voltage			0.8	V
I_{IK} Input clamp current			–18	mA
I_{OH} High-level output current			–15	mA
I_{OL} Low-level output current			64	mA
T_A Operating free-air temperature	0		70	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN74F125 QUADRUPLE BUS BUFFER GATE WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	TYP†	MAX	UNIT
V_{IK}	$V_{CC} = 4.5\text{ V}$,	$I_I = -18\text{ mA}$			-1.2	V
V_{OH}	$V_{CC} = 4.5\text{ V}$	$I_{OH} = -3\text{ mA}$	2.4	3.3		V
		$I_{OH} = -15\text{ mA}$	2	3.1		
	$V_{CC} = 4.75\text{ V}$,	$I_{OH} = -3\text{ mA}$	2.7			
V_{OL}	$V_{CC} = 4.5\text{ V}$,	$I_{OL} = 64\text{ mA}$		0.4	0.55	V
I_I	$V_{CC} = 0$,	$V_I = 7\text{ V}$			0.1	mA
I_{IH}	$V_{CC} = 5.5\text{ V}$,	$V_I = 2.7\text{ V}$			20	μA
I_{IL}	$V_{CC} = 5.5\text{ V}$,	$V_I = 0.5\text{ V}$			-20	μA
I_{OZH}	$V_{CC} = 5.5\text{ V}$,	$V_O = 2.7\text{ V}$			50	μA
I_{OZL}	$V_{CC} = 5.5\text{ V}$,	$V_O = 0.5\text{ V}$			-50	μA
I_{OS}^\ddagger	$V_{CC} = 5.5\text{ V}$,	$V_O = 0$	-100		-225	mA
I_{CCH}	$V_{CC} = 5.5\text{ V}$,	Outputs open		17	24	mA
I_{CCL}	$V_{CC} = 5.5\text{ V}$,	Outputs open		28	40	mA
I_{CCZ}	$V_{CC} = 5.5\text{ V}$,	Outputs open		25	35	mA

† All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

‡ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

switching characteristics (see Figure 1)

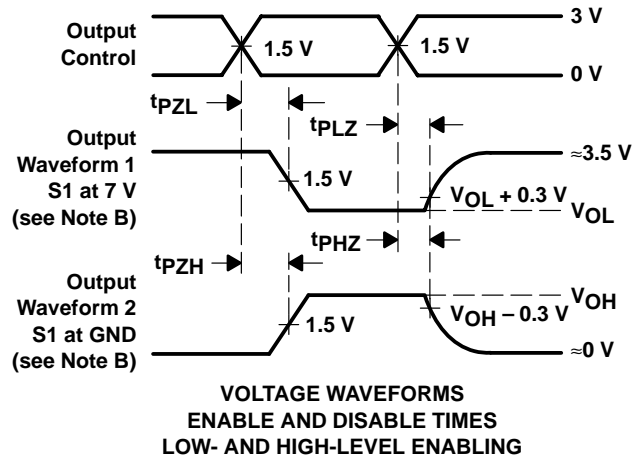
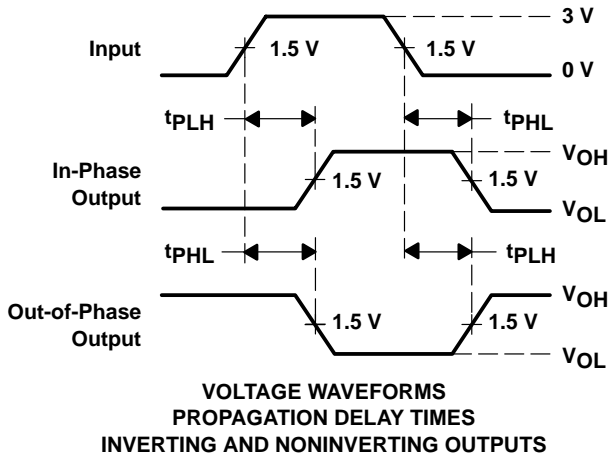
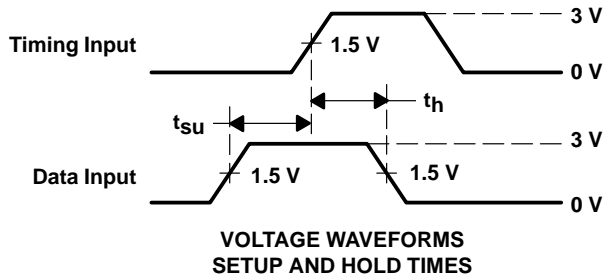
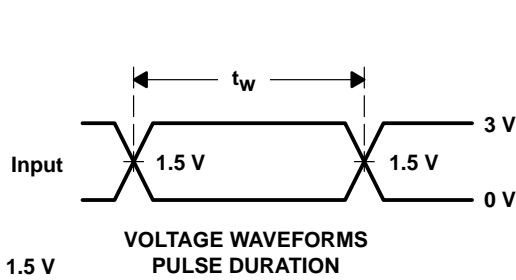
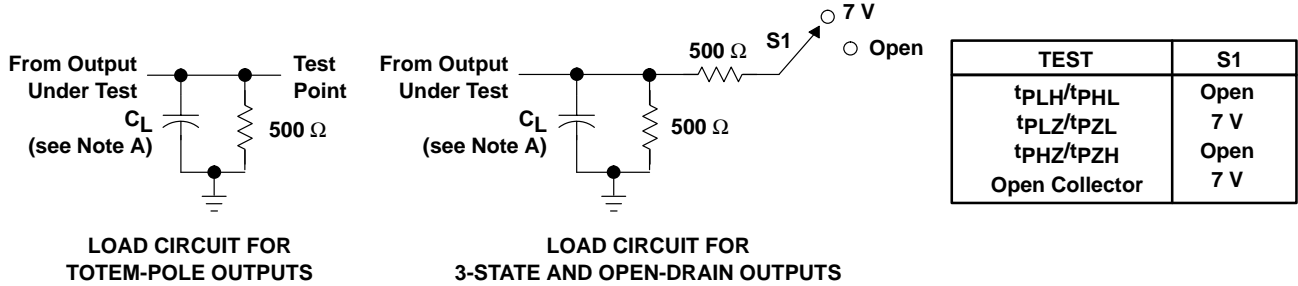
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5\text{ V}$, $C_L = 50\text{ pF}$, $R_L = 500\ \Omega$, $T_A = 25^\circ\text{C}$			$V_{CC} = 4.5\text{ V to }5.5\text{ V}$, $C_L = 50\text{ pF}$, $R_L = 500\ \Omega$, $T_A = \text{MIN to MAX}^\S$		UNIT
			MIN	TYP	MAX	MIN	MAX	
t_{PLH}	A	Y	1.2	3.6	6	1.2	6.5	ns
t_{PHL}			2.2	5.1	7.5	2.2	8	
t_{PZH}	\overline{OE}	Y	2.7	5.1	7.5	2.7	8.5	ns
t_{PZL}			3.2	5.6	8	3.2	9	
t_{PHZ}	\overline{OE}	Y	1	3.1	5	1	6	ns
t_{PLZ}			1	3.1	5.5	1	6	

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

SN74F125 QUADRUPLE BUS BUFFER GATE WITH 3-STATE OUTPUTS

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PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$, duty cycle = 50%.
 - D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74F125D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F125DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F125DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F125DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F125DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F125DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F125N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74F125NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74F125NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F125NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

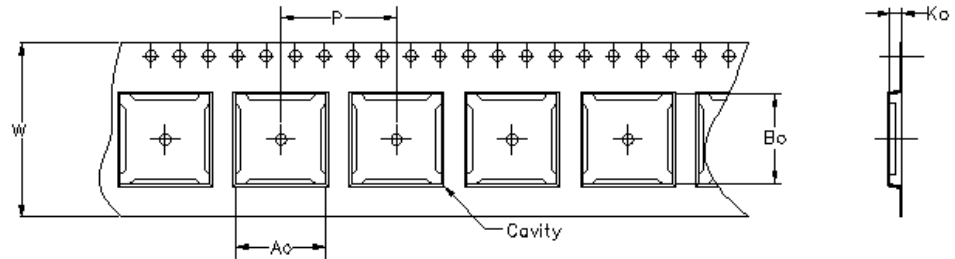
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

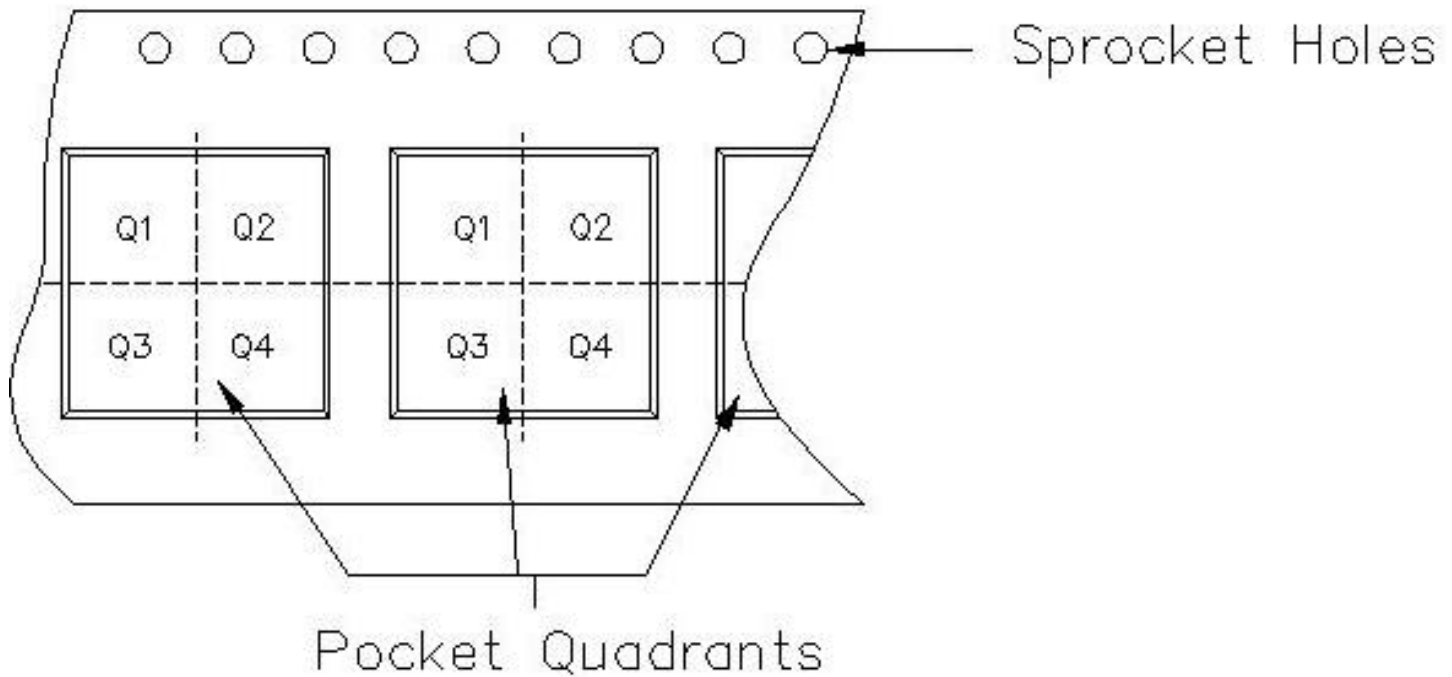
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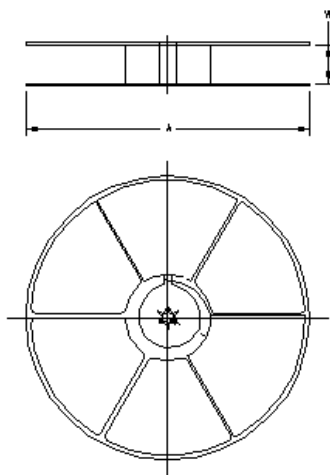
Carrier tape design is defined largely by the component length, width, and thickness.

A_0 = Dimension designed to accommodate the component width.
B_0 = Dimension designed to accommodate the component length.
K_0 = Dimension designed to accommodate the component thickness.
W = Overall width of the carrier tape.
P = Pitch between successive cavity centers.



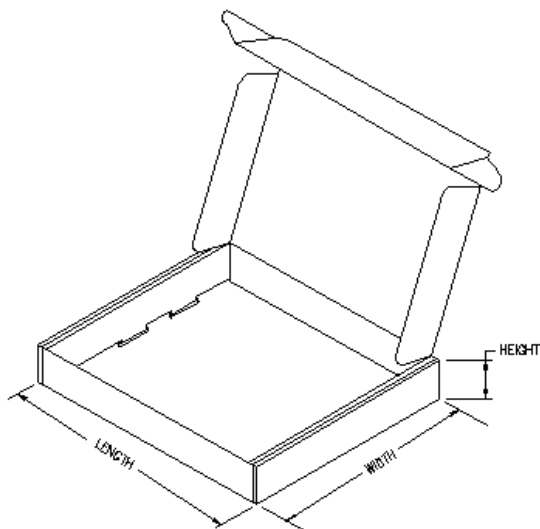
TAPE AND REEL INFORMATION

Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74F125DR	D	14	MLA	330	16	6.5	9.0	2.1	8	16	Q1
SN74F125NSR	NS	14	MLA	330	16	8.2	10.5	2.5	12	16	Q1



TAPE AND REEL BOX INFORMATION

Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
SN74F125DR	D	14	MLA	342.9	336.6	28.58
SN74F125NSR	NS	14	MLA	342.9	336.6	28.58

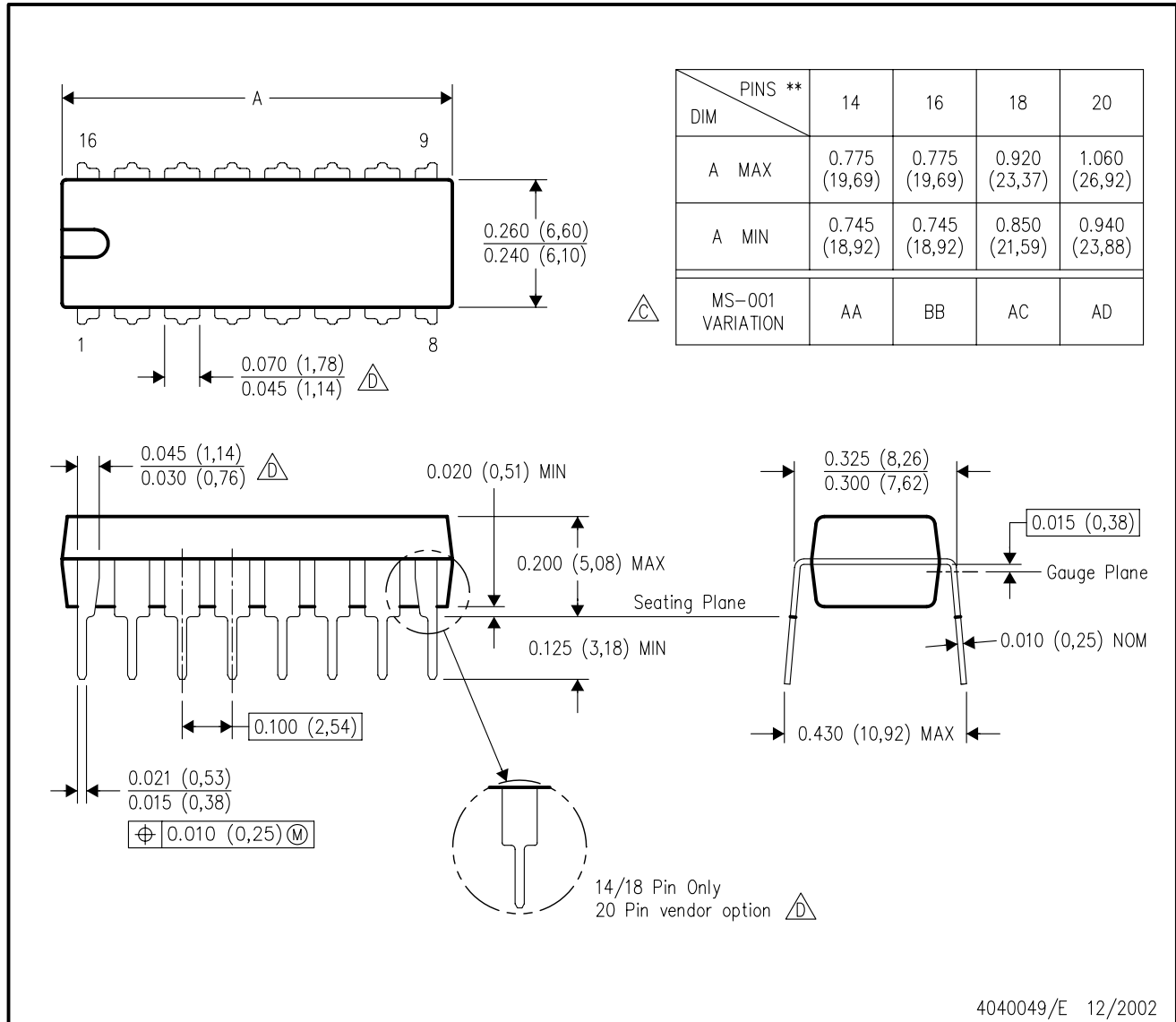


MECHANICAL DATA

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



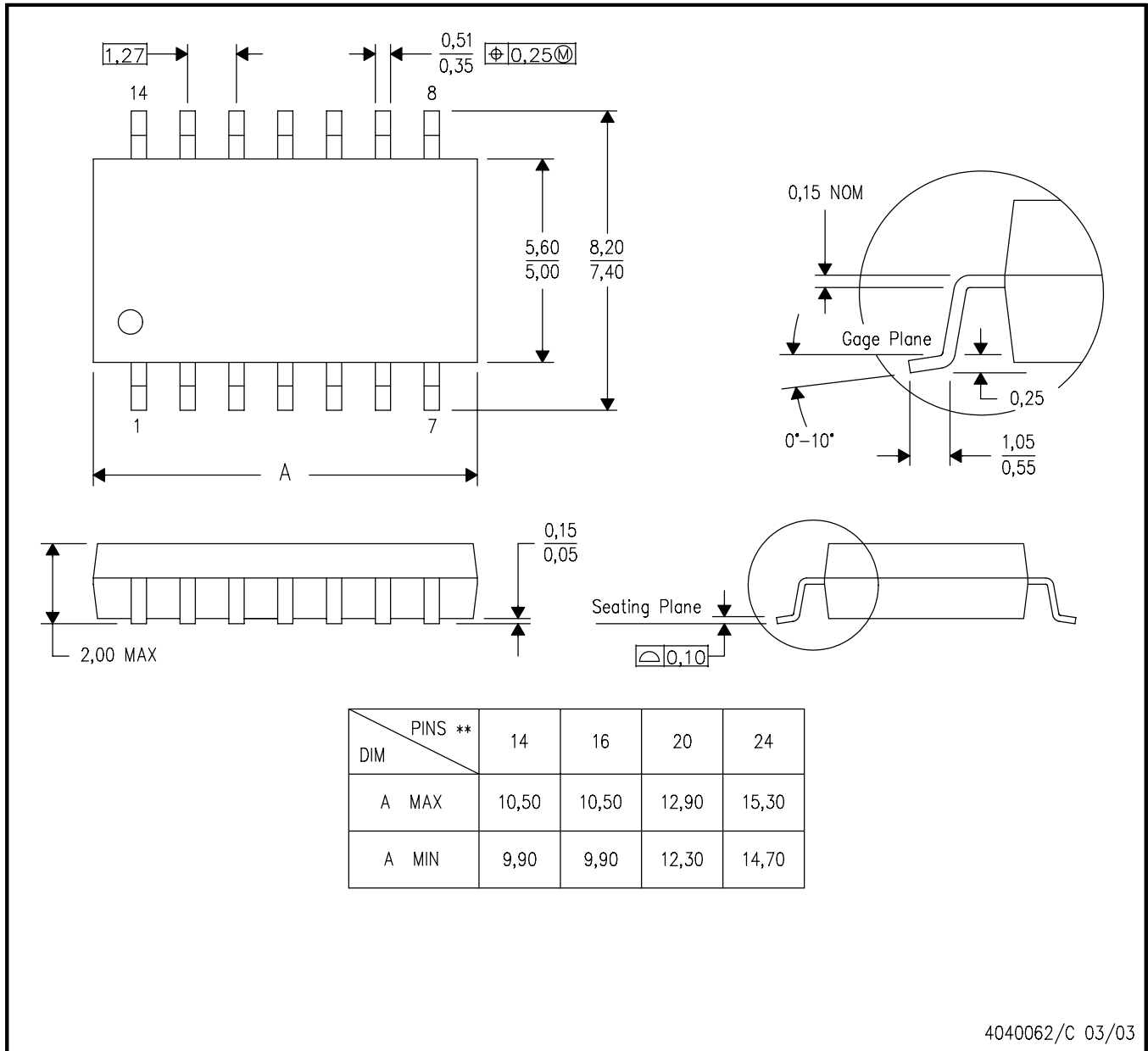
- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

MECHANICAL DATA

NS (R-PDSO-G)**

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



4040062/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.